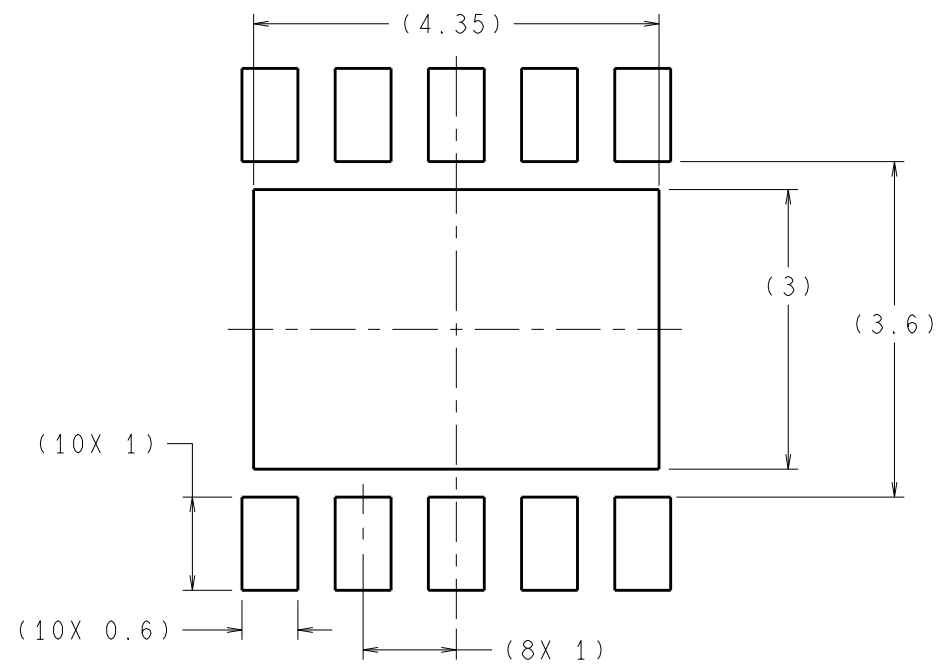
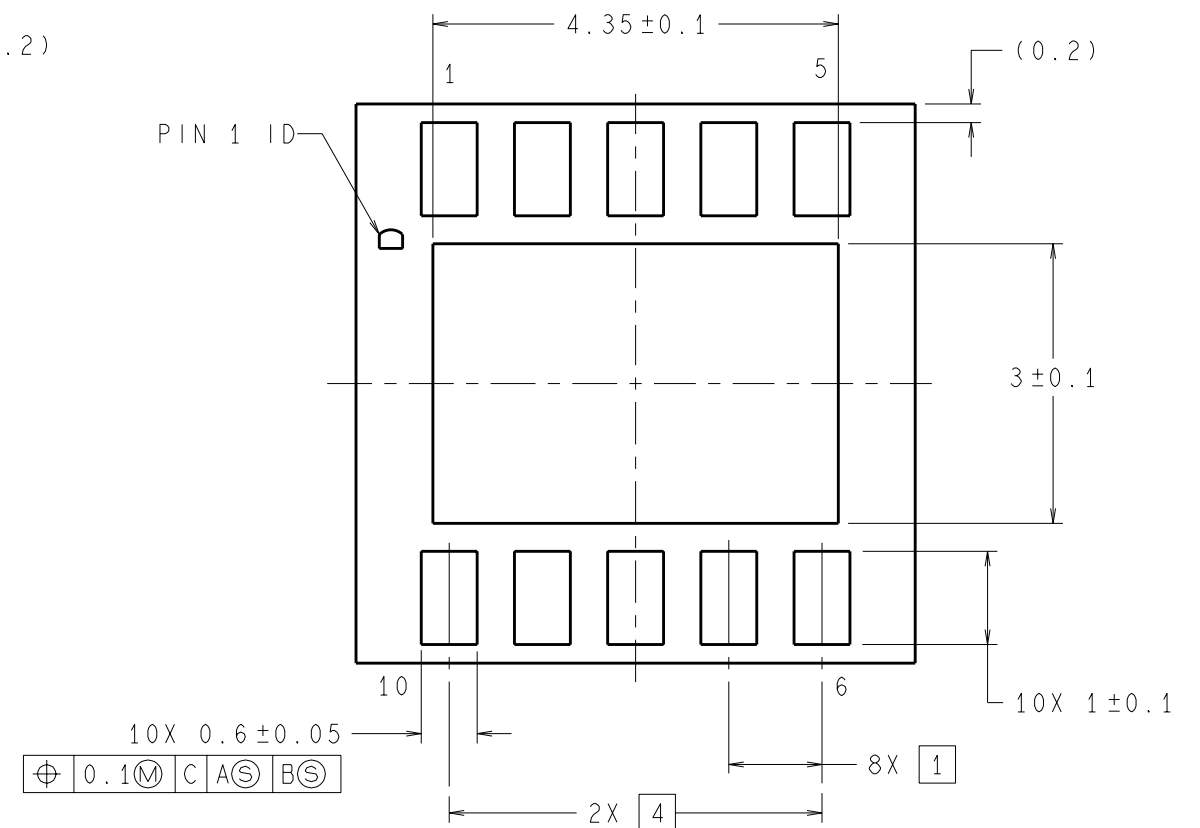
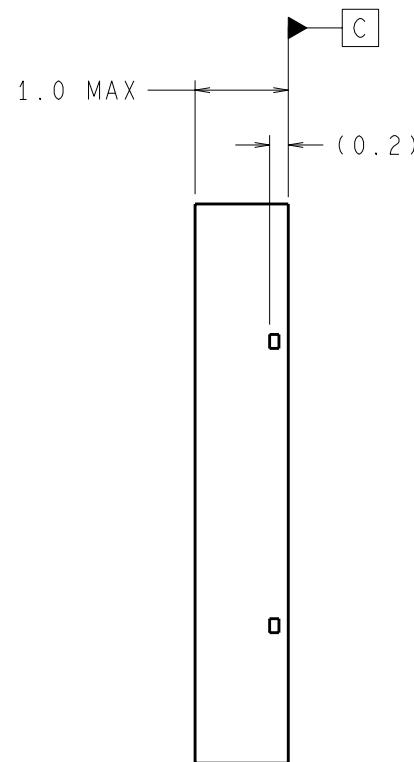
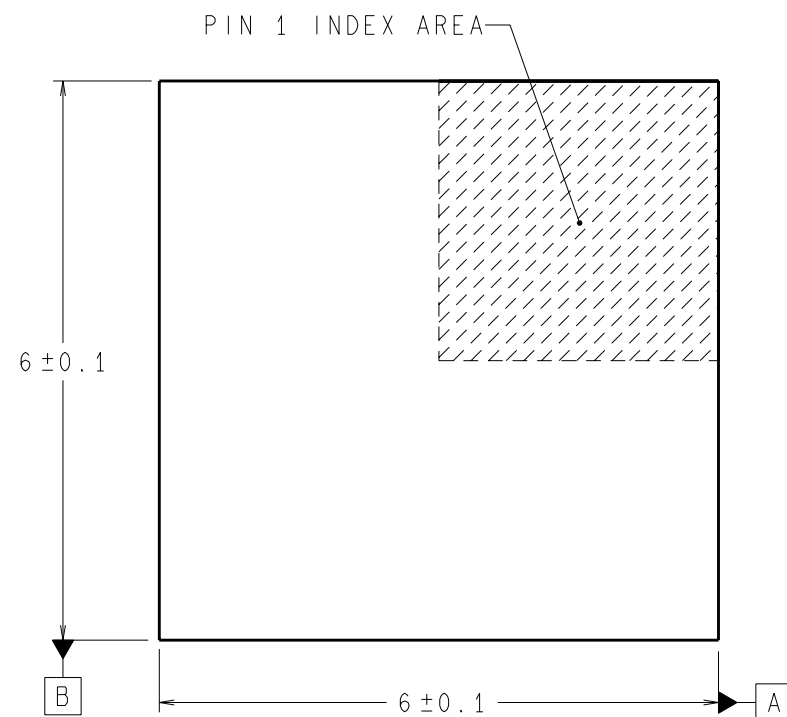


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12602	12/08/2000	AS/TL/NS
B	CHANGE EXPOSED LEAD PAD WIDTH AND RECOMMENDED LAND PATTERN WIDTH (BOTTOM VIEW) FROM 0.7±0.05 TO 0.6±0.05	12607	01/12/2001	AS/TL/NS



DIMENSIONS ARE IN MILLIMETERS

RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS



NOTES: UNLESS OTHERWISE SPECIFIED.

- STANDARD LEAD FINISH TO BE 5.08 MICROMETERS MINIMUM LEAD/TIN (SOLDER) ON COPPER.
- NO JEDEC REGISTRATION AS OF JANUARY 2001.

APPROVALS	DATE	National Semiconductor			
DRAWN AFZINIZAM S.	12/08/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DFTG. CHK. THANH LEQUANG	01/12/2001	POWER LLP, PLASTIC, DUAL, 6 X 6 X 1.0 mm BODY, 10 LD, 1.0 mm PITCH			
ENGR. CHK. N. SANTHIRAN	01/12/2001				
		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-LDD10A	REV B
FORMERLY: N/A		SHEET 1 of 1			